BOURNS®

Product Change Notification

DIODES





May, 2018

Bourns® Model CDSOD323-T15SC TVS Diode **CDNBS08-T15CTVS Diode Array**

Change to Wafer Size and Process Sequence

In order to support our fast growing demand and secure continuity of supply for our customers, the Bourns[®] Model CDSOD323-T15SC and CDNBS08-T15C TVS Diode products will now be built on 5-inch wafers instead of 4-inch wafers. The wafers will be processed using new 5-inch capable furnaces and equipment, with optimized 5-inch wafer process steps. The change in wafer size and process is designed to improve manufacturing efficiency. There will be no change to the form, fit, function, quality or reliability of the products.

Affected Part Numbers
CDSOD323-T15SC
CDNBS08-T15C

Evaluation samples are available now.

Implementation dates are as follows:

Date that manufacturing using 4-inch wafers will cease: November 30, 2018 Date that deliveries of products using 5-inch wafers will begin: **December 1, 2018**

First date code using the 5-inch wafers: **1840**

If you have any questions or need additional information, please feel free to contact <u>Customer Service</u>/ Inside Sales.

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Users should verify that the described changes will not impact the performance of the product in their specific applications.

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